

B1 A conductive layer 13 is then formed using conventional techniques on the dielectric layer 11 (FIG. 3). The conductive layer 13 may be patterned to define an RF component 10, as shown in FIGS. 4 and 5. Again, conventional lithographic and etch techniques known in the art may be used to pattern the conductive layer 13. The conductive layer may be aluminum, for example, although those of skill in the art will appreciate that other suitable conductors may be used as well. The conductive layer 13 of a typical RF component may be patterned to be an inductor or a capacitor, for example, though other circuit configurations are also possible.

**IN THE CLAIMS:**

(1) Kindly amend Claim 1 as follows:

- B2 1. (Amended) A method for making a radiofrequency (RF) component comprising:
- forming a dielectric layer on a semiconductor substrate;
  - forming and patterning a conductive layer on the dielectric layer to define the RF component;
  - forming a plurality of openings on opposing sides and through the RF component at least to the semiconductor substrate, the openings having a diameter ranging from about 0.5 to about 20 microns and substantially uniform spacing between adjacent openings in a range of about 20 to about 200 microns; and
  - releasing the RF component from the semiconductor substrate by exposing the semiconductor substrate to a dry etchant comprising  $\text{XeF}_2$  passing through the at least one opening to the semiconductor substrate.

(2) Kindly cancel ~~Claims~~ 2-3 without prejudice or disclaimer.